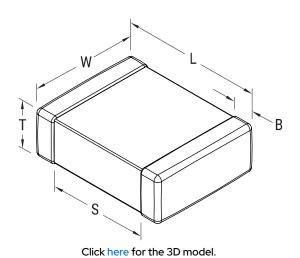


C0603X561G2TACTU

Aliases (C0603X561G2TAC7867)

SMD Comm X8G HT150C Flex, Ceramic, 560 pF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

560 pF

0% Loss/Decade Hour: Referee

Time is 1000 Hours

100 GOhms

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

	Measurement Condition	1 MHz 1.0Vrms
	Tolerance	2%
	Voltage DC	200 VDC
	Dielectric Withstanding Voltage	500 VDC
n	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
r Tape	Capacitance Change with Reference to +25°C and 0 VDC	30 ppm/C, 1MegaHz 1.0Vrms
Applied (TCC)	,	
	Dissipation Factor	0.1% 1 MHz 1.0Vrms

Specifications

Capacitance

Aging Rate

Insulation Resistance

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 05/05/2025 © 2006 - 2025 YAGEO